

AT A GLANCE

Ultra-fast, low-loss and flexible electrical interconnects for opto-electrical packaging.



Features

Polymer embedded electrical coplanar waveguides.

- Bandwidth > 200 GHz
- Customized design
- mm to cm scale

Applications

High speed flexible electrical chip to chip interconnect:

- Driver-to-LD
- PD-to-TIA

Technical Background

Ultra-fast, low-loss and flexible electrical coplanar waveguides for interconnecting drivers to laser and photodetectors to transimpedance amplifiers (TIAs) with bandwidths exceeding 200 GHz.

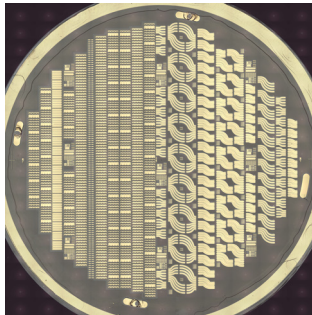
Fabricated on wafer scale.

Customized design available.

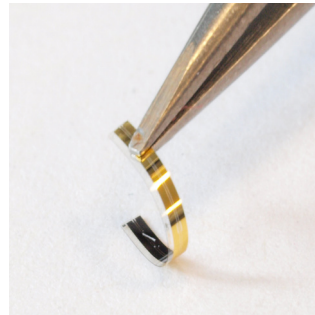
References

International R&D projects
 PHOENICS
 POETICS
 POLYNICES
 QSNP
 Qu-Test / Qu-Pilot
 SPRINTER
 TERA 6G
 TERAMEASURE
 TERAWAY
 (funded by EU commission)

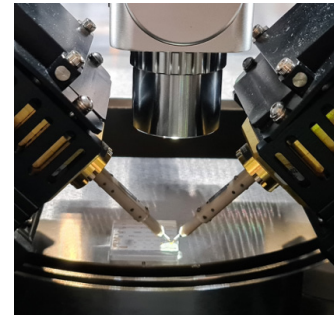
Characteristics



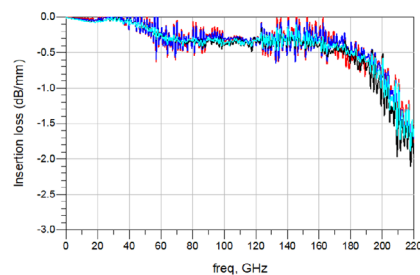
*Fabrication on wafer scale,
 customized design*



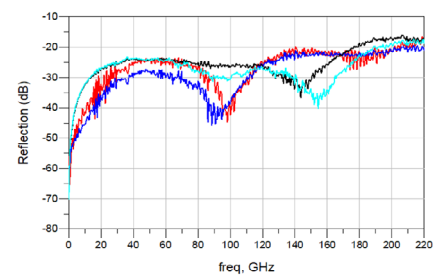
Flexible electrical interconnects



RF characterization set-up



Transmission: >> 200 GHz



Reflection: <-20 dB

Applications

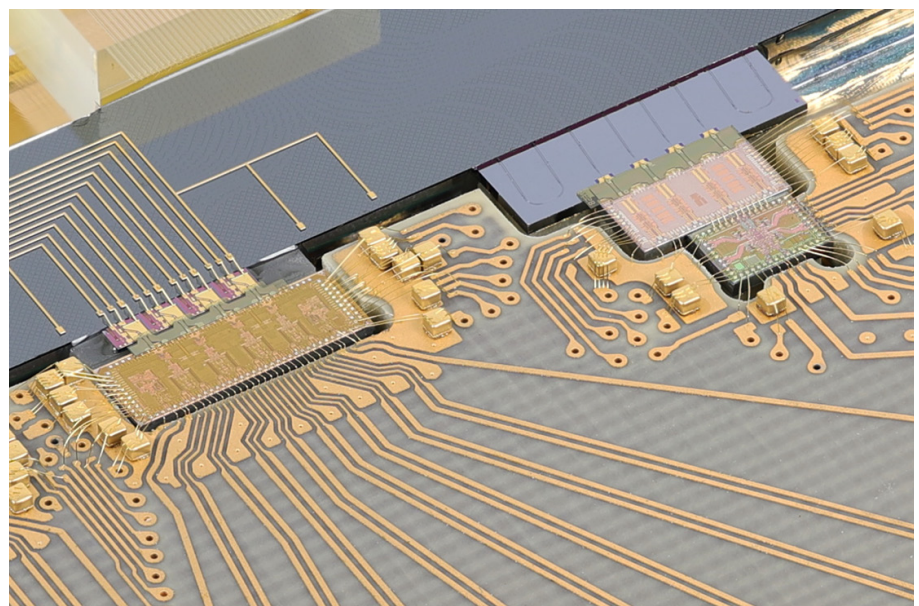


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1.6 Tbit/s optical transceiver with FlexLines for intra datacenter connectivity (EU POETICS).